



SN 10/756,901

PATENTIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar

Examiner: Sheila Clark

Serial No.: 10/756,901

Group Art Unit: 2815

Filed: January 14, 2004

Docket: 303.572US2

Title: SELECTIVE DEPOSITION OF SOLDER BALL CONTACTS

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicant would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/134363 6,136,689	August 14, 1998	M4065.082/P082	METHOD OF FORMING A MICRO SOLDER BALL FOR USE IN C4 BONDING PROCESS
11/003119	December 3, 2004	303.572US3	SELECTIVE DEPOSITION OF SOLDER BALL CONTACTS

Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicant requests that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

Respectfully submitted,

PAUL A. FARRAR

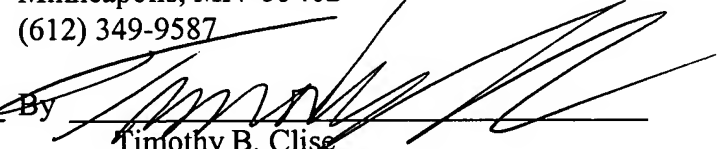
By Applicant's Representatives,

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Date

24 May '05

By


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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 24 day of May, 2005.

Name



Signature

